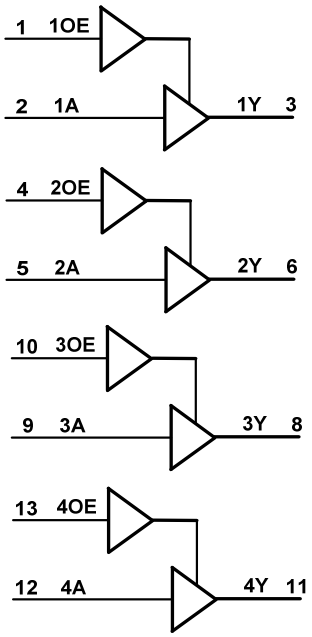
Pin Descriptions

Pin Number	Pin Name	Function
1	1OE	Data Enable Input (active low)
2	1A	Data Input
3	1Y	Data Output
4	2OE	Data Enable Input (active low)
5	2A	Data Input
6	2Y	Data Output
7	GND	Ground
8	3Y	Data Output
9	3A	Data Input
10	3OE	Data Enable Input (active low)
11	4Y	Data Outp
12	4A	Data Input
13	4OE	Data Enable Input (active low)
14	Vcc	Supply Voltage

Logic Diagram



Function Table

Inputs		Output
OE	A	Y
H	H	H
H	L	L
L	X	Z

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Absolute Maximum Ratings (Note 4) (@T_A = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD CDM	Charged Device Model ESD Protection	1	KV
ESD MM	Machine Model ESD Protection	200	V
V_{CC}	Supply Voltage Range	-0.5 to +7.0	V
V_I	Input Voltage Range (Note 5)	-0.5 to +7.0	V
I_{IK}	Input Clamp Current V_I < -0.5V or Vi > V_{CC} +0.5V	±20	mA
I_{OK}	Output Clamp Current V_O < -0.5V or V_O > V_{CC} +0.5V	±20	mA
I_O	Continuous Output Current -0.5V < V_O V_{CC} +0.5V	+/- 25	mA
I_{CC}	Continuous Current Through V_{CC}	50	mA
I_{GND}	Continuous Current Through GND	-50	mA
T_J	Operating Junction Temperature	-40 to +150	°C
T_{STG}	Storage Temperature	-65 to +150	°C
P_{TOT}	Total Power Dissipation	500	mW

Notes: 4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
5. Input Voltage cannot exceed V_{CC} to the extent the Maximum clamp current is exceeded.

Recommended Operating Conditions (Note 6) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	Supply Voltage		2.0	6.0	V
V_I	Input Voltage		0	V_{CC}	V
V_O	Output Voltage		0	V_{CC}	V
Δt/ΔV	Input Transition Rise or Fall Rate	V_{CC} = 2.0V		625	ns/V
		V_{CC} = 4.5V		140	
		V_{CC} = 6.0V		85	
T_A	Operating Free-Air Temperature		-40	+125	°C

Note: 6. Unused inputs should be held at V_{CC} or ground.

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Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Test Conditions	V_{CC}	T_A = -40°C to +85°C		T_A = -40°C to +125°C		Unit
				Min	Max	Min	Max	
V_{IH}	High-level Input Voltage		2.0V	1.5		1.5		V
			4.5V	3.15		3.15		
			6.0V	4.2		4.2		
V_{IL}	Low-level input voltage		2.0V		0.5		0.5	V
			4.5V		1.35		1.35	
			6.0V		1.8		1.8	
V_{OH}	High-level Output Voltage	I_{OH} = -20µA	2.0V	1.9		1.9		V
		I_{OH} = -20µA	4.5V	4.4		4.4		
		I_{OH} = -20µA	6.0V	5.9		5.9		
		I_{OH} = -4.0mA	4.5V	3.84		3.7		
		I_{OH} = -5.2mA	6.0V	5.34		5.2		
V_{OL}	Low-level Output Voltage	I_{OL} = 20µA	2.0V		0.1		0.1	V
		I_{OL} = 20µA	4.5V		0.1		0.1	
		I_{OL} = 20µA	6.0V		0.1		0.1	
		I_{OL} = 4mA	4.5V		0.33		0.44	
		I_{OL} = 5.2mA	6.0V		0.33		0.44	
I_{OZ}	Z State Leakage Current	V_O = 0 to 6.0V V_I = GND or 6.0V	6.0V		± 5.0		± 10	µA
I_I	Input Current	V_I = GND to 5.5V	6.0V		± 1		± 1	µA
I_{CC}	Supply Current	V_I = GND or V_{CC}, I_O=0	6.0V		20		40	µA

Switching Characteristics

Symbol	Parameter	Test Conditions	V_{CC}	T_A = +25°C			-40°C to +85°C	-40°C to +125°C	Unit
				Min	Typ	Max	Max	Max	
t_{PD}	Propagation Delay A_N to Y_N	Figure 1 C_L = 50pF	2.0V	—	30	100	125	150	ns
			4.5V	—	11	20	25	30	
			6.0V	—	9	17	21	26	
t_{EN}	Enable Time $\overline{OE}_N$ to Y_N	Figure 1 C_L = 50pF	2.0V	—	41	125	155	190	ns
			4.5V	—	15	25	31	38	
			6.0V	—	12	21	26	32	
t_{DIS}	Disable Time $\overline{OE}_N$ to Y_N	Figure 1 C_L = 50pF	2.0V	—	41	125	155	190	ns
			4.5V	—	15	25	31	38	
			6.0V	—	12	21	26	32	
t_t	Transition Time	Figure 1 C_L = 50pF	2.0V	—	14	60	75	90	ns
			4.5V	—	5	12	15	18	
			6.0V	—	4	10	13	15	

Operating Characteristics (@T_A = +25°C, unless otherwise specified.)

Parameter		Test Conditions	V_{CC} = 6V	Unit
			Typ	
C_{pd}	Power Dissipation Capacitance per Gate	f = 1 MHz	22	pF
C_I	Input Capacitance	V_I = V_{CC} – or GND	4	pF

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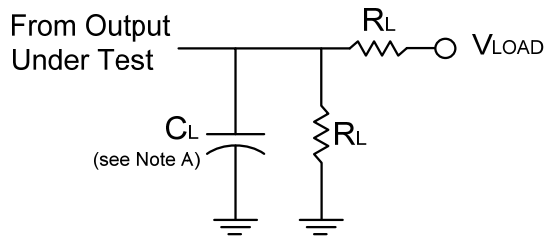
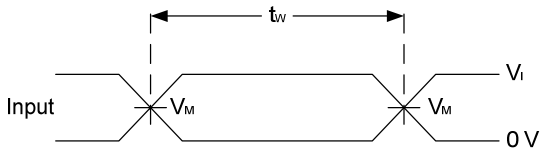
Parameter Measurement Information

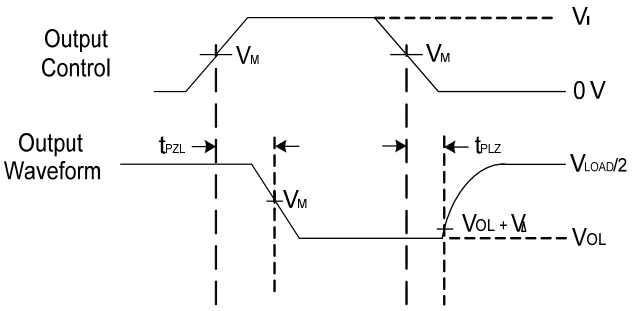


TEST	Condition
t_{PLZ} (see Notes D and E)	Vload
t_{PZL}(see Notes D and F)	Vload

V_{CC}	Inputs		V_M	V_{LOAD}	C_L	R_L	$V\Delta$
	V_I	t_r/t_f					
2.0V to 6.0V	V_{CC}	≤3ns	$V_{CC}/2$	2 X V_{CC}	15,50 pF	2 KΩ	10% of V_{CC}



Voltage Waveform
Pulse Duration



Voltage Waveform
Propagation Delay Times

Figure 1 Load Circuit and Voltage Waveforms

Notes: A. Includes test lead and test apparatus capacitance.
B. All pulses are supplied at pulse repetition rate ≤ 1 MHz
C. The inputs are measured one at a time with one transition per measurement.
D. For the 3 state device t_{PLZ} and t_{PZL} are the same as t_{PD}.
E. t_{PZL} is measured at V_M.
D. t_{PLZ} is measured at V_{OL} +V_Δ

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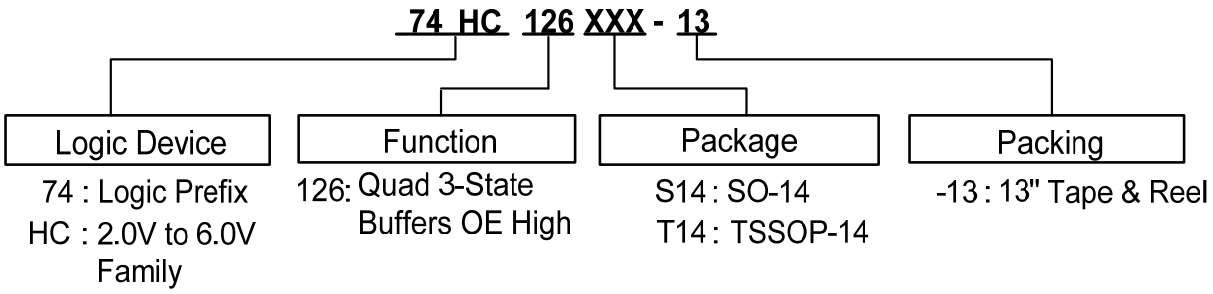
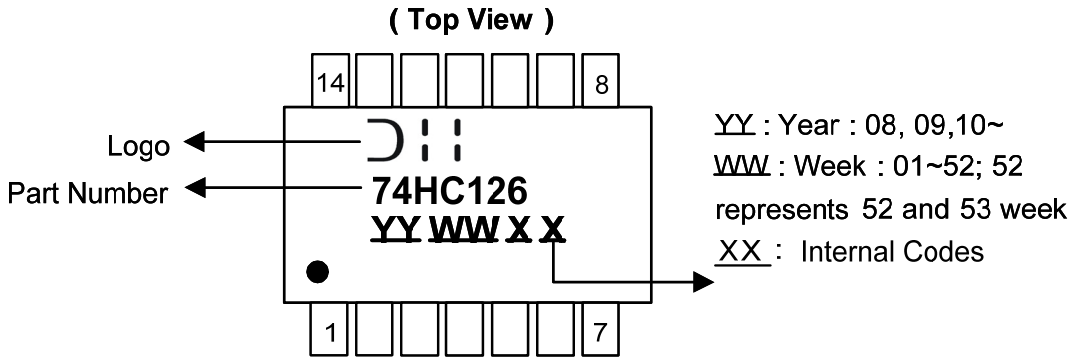
Ordering Information



Device	Package Code	Packaging	7" Tape and Reel	
			Quantity	Part Number Suffix
74HC126S14-13	S14	SO-14	2500/Tape & Reel	-13
74HC126T14-13	T14	TSSOP-14	2500/Tape & Reel	-13

Marking Information

(1) SO-14, TSSOP-14



Part Number	Package
74HC126S14	SO-14
74HC126T14	TSSOP-14

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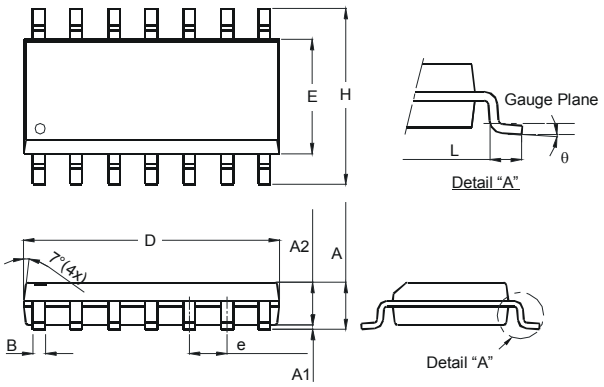
Package Outline Dimensions (All dimensions in mm.)

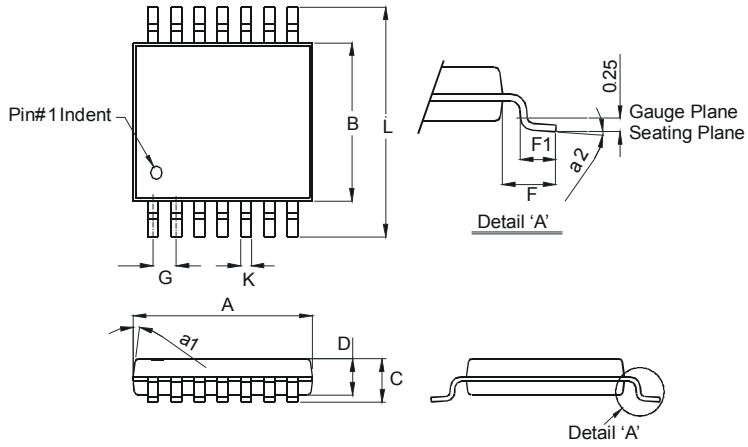
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

Package Type: SO-14



SO-14		
Dim	**Min**	**Max**
A	1.47	1.73
A1	0.10	0.25
A2	1.45 Typ	
B	0.33	0.51
D	8.53	8.74
E	3.80	3.99
e	1.27 Typ	
H	5.80	6.20
L	0.38	1.27
θ	0°	8°
All Dimensions in mm		

Package Type: TSSOP-14



TSSOP-14		
Dim	**Min**	**Max**
a1	7° (4X)	
a2	0°	8°
A	4.9	5.10
B	4.30	4.50
C	—	1.2
D	0.8	1.05
F	1.00 Typ	
F1	0.45	0.75
G	0.65 Typ	
K	0.19	0.30
L	6.40 Typ	
All Dimensions in mm		

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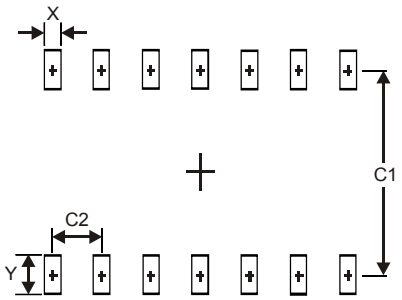
Suggested Pad Layout

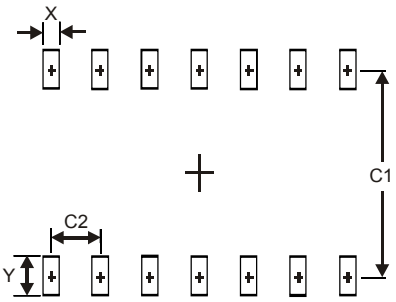
Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.

Package Type: SO-14



Dimensions	Value (in mm)
X	0.60
Y	1.50
C1	5.4
C2	1.27

Package Type: TSSOP-14



Dimensions	Value (in mm)
X	0.45
Y	1.45
C1	5.9
C2	0.65

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